PicoTrack

semi MEMBER
www.picotrack.com

309 Laurelwood Rd #21
Santa Clara, CA 95054
Main: (408)988-7000
Fax: (408)988-7091

PCT-150BE TRACK SYSTEM

MASS PRODUCTION WITH DUAL TRACKS (1 COATER, 1 DEVLOPER) TOOL SET

Please contact Sales sales@picotrack.com for more information

309 Laurelwood Rd #21
Santa Clara, CA 95054
Main: (408)988-7000
Fax: (408)988-7091

Track System Specification	Description
System designed	US Standard System
System Configuration	TRACK 2: SEND - DEV.(MD.) – HPO – REC TRACK 1: SEND - VPO - CP - COATER - HPO - REC
System dimension	Length: 58.50”, Width: 35.50”, Height: 60”
Wafer Sensor	Capacity or Optical
Wafer material	Silicon/Sapphire/GaAs/ Ceramic…
Wafer shape	Round/square/rectangular
System Controller	PC & PLC Controller with Windows OS based
Chemical canister cabinet	Solvent (EBR, HMDS, Cleaning…), developer liquid
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles
Indexer wafer cassette	4, (available upon request)
Wafer size	Up to 6’’ (150mm)
System Enclosure and windows	Optional
Coater	**1 Module**
Maximum spin speed	6000 rpm
Spin motor	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Dispense arm accuracy	± 0.1 mm
Wafer centering accuracy	± 0.1 mm
Dispense arm motion control	Stepper motor & driver
Dispense arm nozzles (STD)	3x or more (3/16’’ or 1/4’’ OD)
Dispense method	Static/traverse
Pre-dispense function	Yes
Top/Bottom EBR	Yes
Catch-cup rinse(CCR)	Optional
Cleaning tip nozzle	Optional
Photoresit temperature control	Optional ≤ 1°C (10-50°C range)
Wafer transfer	O-ring belt
Developer Module	**1 Module**
Maximum spin speed	6000 rpm
Spin motor	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Spin direction	Clockwise (+) & counter clockwise (-)
Dispense arm motion control	Stepper motor and driver
Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm nozzles (STD)	1 Spray+ 1 Stream or 2 sprays+ 2 streams
Developer dispense type	Stream, Puddle, Fan spray, Cone spray….
Dispense method	Static, traverse, sweep
DI water top and back side rinse	Yes
N2 Airing back side	Yes
N2 Blow-off top nozzle	Optional
Developer fluid temperature control	Optional ≤ 1°C (10-50°C range)
Wafer transfer	O-ring belt

309 Laurelwood Rd #21
Santa Clara, CA 95054
Main: (408)988-7000
Fax: (408)988-7091

VPO Module	**1 Module**
VPO block type	Aluminum with vacuum slots
VPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	Up to 200°C, Δt: 50°C ≤ 200s
Temperature uniformity	± 1°C (25-15°0C), ± 2°C (151-200°C)
Prime method	Pressurize N2 with bubbler
Wafer contact angle	≥ 65° on prime silicon wafer
Contact angle uniformmity	≤ 1.5° on prime base silicon wafer
Wafer Carrier	02 rails controlled by stepper motor
Bake method	Proximity, contact, vacuum & purge bake
Wafer transfer	O-ring belt
HPO Module	**2 Modules**
HPO block type	Aluminum anodized with vacuum slots or proximity
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature Themal Probe	RTD or TC
Wafer up/down motion control	Stepper motor and driver
Temperature range	25-250°C, Δt: 50°C ≤ 200s, (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Bake method	Contact/ Proximity bake/ or fixed proximity
Wafer transfer	O-ring belt
Chill Plate	**1 Modules**
Chill Plate block type	Aluminum anodized with vacuum slots
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Wafer up/down motion control	DC motor and driver
Wafer Sensor	Optical
Wafer transfer	O-ring belt
Cooling Water Temperature controller	Optional